

Appl. No. 10/712,471
 Amdt. Dated September 20, 2006
 Reply to Office Action of July 6, 2006

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the above-identified application:

1. (currently amended): A passive thermal switch assembly, comprising:
 a heat pipe having an evaporator end and a condenser end, the heat pipe evaporator end adapted to couple to a heat source;
 a first thermally conductive contact coupled to the heat pipe condenser end;
 a link comprised at least partially of a shape memory metal or metal alloy, the link coupled to the first thermally conductive contact and adapted to couple to a heat sink; and
 a second thermally conductive contact disposed proximate the first thermally conductive contact and adapted to couple to the heat sink,
 wherein the link moves the first thermally conductive contact to at least partially engage the second thermally conductive contact when at least the link is [[at or]] above a predetermined temperature, and to disengage the second thermally conductive contact when at least the link is below the predetermined temperature.

2-13 (canceled).

14. (previously presented): The switch assembly of Claim 1, wherein the shape memory alloy is selected from the group consisting of nickel-titanium, copper-zinc-aluminum, and iron-manganese-silicon.

15-16 (canceled).

17. (currently amended) An electronic equipment enclosure, comprising:
 a chassis;
 one or more circuit components housed within the chassis;
 one or more heat pipes each having an evaporator end and a condenser end, each heat pipe evaporator end coupled to at least one of the circuit components;

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one or more switches coupled to each heat pipe condenser end, each switch comprised at least partially of a material having a shape or volume that varies with temperature and disposed adjacent the chassis, whereby each switch is selectively thermally coupled to, and thermally decoupled from, the chassis at a predetermined temperature, each switch comprising:

a first thermally conductive contact coupled to the heat pipe condenser end;

a link comprised at least partially of a shape memory metal or metal alloy, the link coupled to the first thermally conductive contact and to the chassis; and

a second thermally conductive contact disposed proximate the first thermally conductive contact and coupled to the chassis,

wherein the first and second thermally conductive contacts at least partially engage one another when at least the link is [[at or]] above a predetermined temperature, and to disengage when at least the link is below the predetermined temperature.

18-29 (canceled).

30. (previously presented): The system of Claim 17, wherein the shape memory alloy is selected from the group consisting of nickel-titanium, copper-zinc-aluminum, and iron-manganese-silicon.

31-32 (canceled).